

In the Specification:

Please amend paragraph 35 as follows:

The socket 20 shown in Figures 3 and 4 does not have a conventional nest in the receiving area 52. As explained above in the background section, a conventional nest holds the packaged device in the socket in a manner that protects the solder balls from being damaged and aligns the solder balls with corresponding leads of the socket. The testing system 10 shown in Figure 1 protects the solder balls and aligns the solder balls with the leads without a nest by (a) providing a guide that protects the solder balls of packaged devices irrespective of the package profile and (b) aligning the solder balls with leads using the placement heads 26 (Figure 1). Figures 5-9 describe several embodiments of the guides that are removably attachable to the sockets 20 for protecting the solder balls from being damaged as they contact the leads 42 (Figure 456). Figures 10-13 then describe several embodiments of placement heads that align the packaged devices with the sockets 20 so that the solder balls contact the correct leads.

Please amend paragraph 38 as follows:

As best seen in Figures 5 and 6, the guide 56 of the illustrated embodiment includes a plurality of retention members 60 that removably retain the guide in the receiving area 52 of the socket 20 at a desired position relative to the array of leads 42. The retention members 60 of the illustrated embodiment have hook portions 62 (Figure 5) that engage the base 40 and securely retain the guide 56 in a fixed position relative to the base. The retention members 60 are configured so the slider 48 can translate laterally (i.e., left-right in Figure 6) relative to the base 40 and the leads 42 when the spring-loaded cover 50 is depressed relative to the base 40. While the illustrated embodiment has retention members 60 with hook portions 62, other embodiments can use other retention devices that removably retain the guide 56 in the receiving area 52. Accordingly, the guide 56 can be removed and replaced in the event a guide is

damaged or if the socket 20 is to be used for testing packaged devices with different ball-grid arrays that require a different shaped or sized guide 56.